2SK3938

Silicon N-channel MOSFET

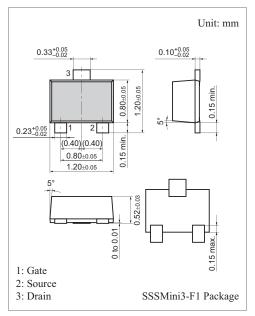
For switching circuits

Features

- High-speed switching
- SSSMini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Drain-source surrender voltage	V _{DSS}	30	V	
Gate-source surrender voltage	V _{GSS}	±12	V	
Drain current	ID	100	mA	
Peak drain current	I _{DP}	200	mA	
Power dissipation	P _D	100	mW	
Channel temperature	T _{ch}	125	°C	
Storage temperature	T _{stg}	-55 to +125	°C	



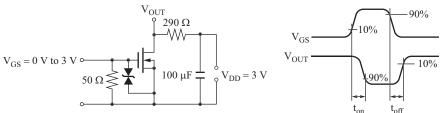
Marking Symbol: 6U

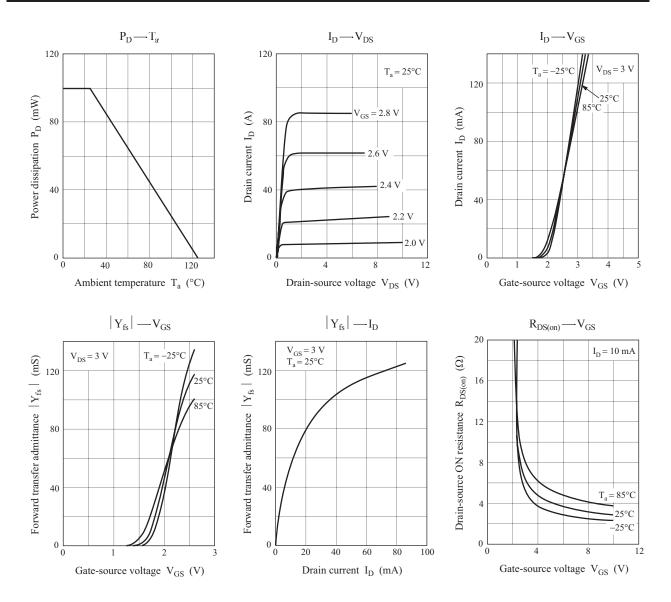
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source surrender voltage	V _{DSS}	$I_D = 10 \ \mu A, V_{GS} = 0$	30			V
Drain-source cutoff current	I _{DSS}	$V_{\rm DS} = 20 {\rm V}, {\rm V}_{\rm GS} = 0$			1.0	μΑ
Gate-source cutoff current	I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0$			±10	μΑ
Gate threshold voltage	V _{TH}	$I_D = 1.0 \ \mu A, V_{DS} = 3 \ V$	0.5	1.0	1.5	V
Drain-source ON resistance	D	$I_D = 10 \text{ mA}, V_{GS} = 2.5 \text{ V}$		7	12	Ω
	R _{DS(on)}	$I_D = 10 \text{ mA}, V_{GS} = 4.0 \text{ V}$		5	8	
Forward transfer admittance	Y _{fs}	$I_D = 10 \text{ mA}, V_{DS} = 3 \text{ V}, f = 1 \text{ kHz}$	20	55		mS
Short-circuit forward transfer capacitance (Common source)	C _{iss}	$V_{DS} = 3 V, V_{GS} = 0, f = 1 MHz$		12		pF
Short-circuit output capacitance (Common source)	C _{oss}			10		pF
Reverse transfer capacitance (Common source)	C _{rss}			6		pF
Turn-on time *	t _{on}	$V_{DD} = 3 V, V_{GS} = 0 V \text{ to } 3 V, I_D = 10 \text{ mA}$		350		ns
Turn-off time *	t _{off}	$V_{DD} = 3 V, V_{GS} = 3 V \text{ to } 0 V, I_D = 10 \text{ mA}$		350		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. * : t_{on} , t_{off} measurement circuit





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